

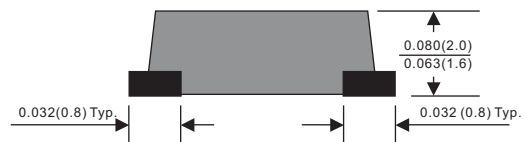
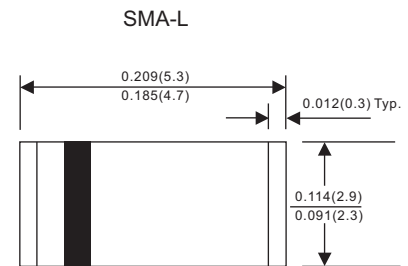
## Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low profile surface mounted application in order to optimize board space.
- High current capability.
- Ultrafast recovery time for high efficiency.
- High surge current capability.
- Glass passivated chip junction.
- **Moisture Sensitivity Level 1**

## Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SMA-L
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.05 gram

## Package outline



Dimensions in inches and (millimeters)

## Maximum ratings and Electrical Characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	$I_o$			2.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	$I_{FSM}$			50	A
Reverse current	$V_R = V_{RRM}$ $T_J = 25^{\circ}\text{C}$	$I_R$			5.0	$\mu\text{A}$
	$V_R = V_{RRM}$ $T_J = 125^{\circ}\text{C}$				150	
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	$C_J$		25		pF
Storage temperature		$T_{STG}$	-55		+150	$^{\circ}\text{C}$

SYMBOLS	$V_{RRM}^{*1}$ (V)	$V_{RMS}^{*2}$ (V)	$V_R^{*3}$ (V)	$V_F^{*4}$ (V)	$t_{rr}^{*5}$ (ns)	Operating temperature $T_J$ , ( $^{\circ}\text{C}$ )
HFM201L	50	35	50	1.00	50	-55 to +150
HFM202L	100	70	100			
HFM203L	200	140	200			
HFM204L	400	280	400	1.30		
HFM205L	600	420	600	1.70	75	
HFM206L	800	560	800			
HFM207L	1000	700	1000			

\*1 Repetitive peak reverse voltage

\*2 RMS voltage

\*3 Continuous reverse voltage

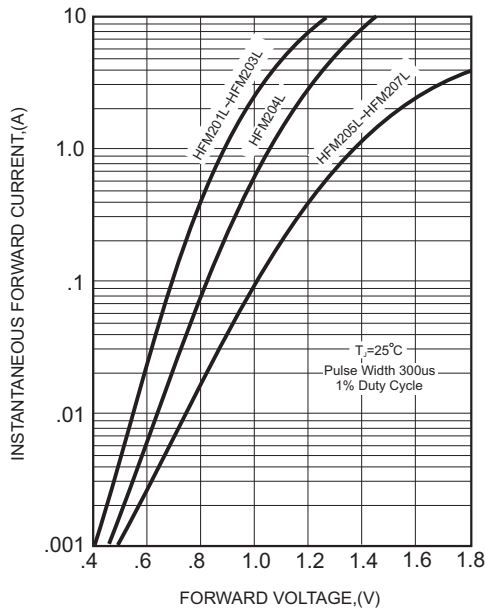
\*4 Maximum forward voltage@ $I_F=2.0\text{A}$

\*5 Maximum Reverse recovery time, note 1

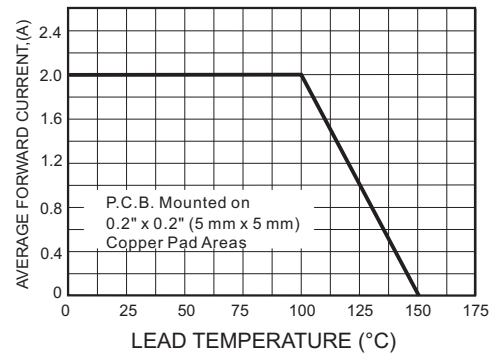
Note 1. Reverse recovery time test condition,  $I_F=0.5\text{A}$ ,  $I_R=1.0\text{A}$ ,  $I_{RR}=0.25\text{A}$

**Rating and characteristic curves**

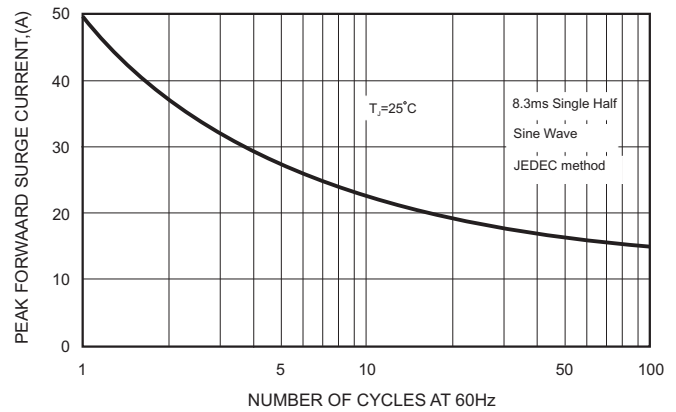
**FIG.1-TYPICAL FORWARD CHARACTERISTICS**



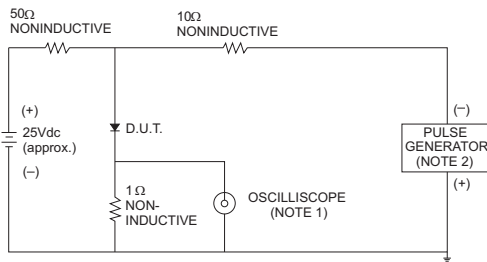
**FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE**



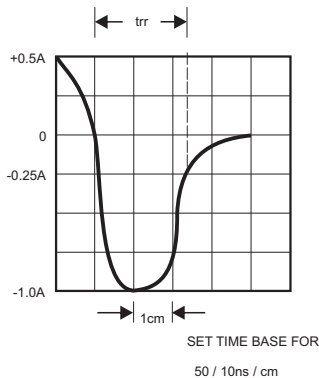
**FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT**



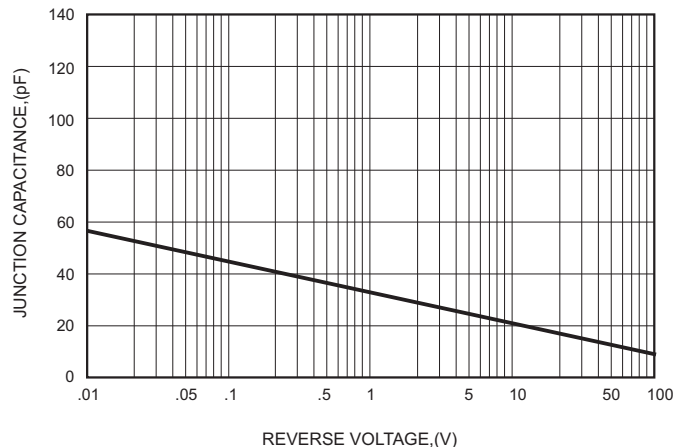
**FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS**



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm.22pF.  
2. Rise Time= 10ns max., Source Impedance= 50 ohms.



**FIG.5-TYPICAL JUNCTION CAPACITANCE**





### Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

### Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMA-L	7"	2,000	4.0	20,000	183*170*183	178	382*356*387	160,000	15.5
SMA-L	13"	7,500	4.0	15,000	337*337*37	330	350*330*360	120,000	14.2

### Marking

Type number	Marking code
HFM201L-TH	H21
HFM202L-TH	H22
HFM203L-TH	H23
HFM204L-TH	H24
HFM205L-TH	H25
HFM206L-TH	H26
HFM207L-TH	H27

Note: L: Package code, SMA-L

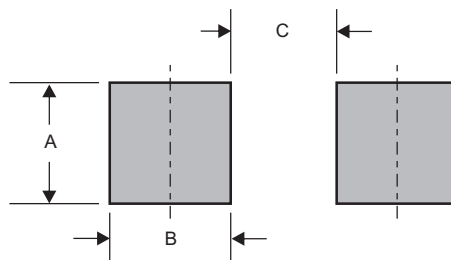
-T: Taping Reel

**Pb-Free package is available**

RoHS product for packing code suffix "G"

Halogen free product for packing code suffix "H"

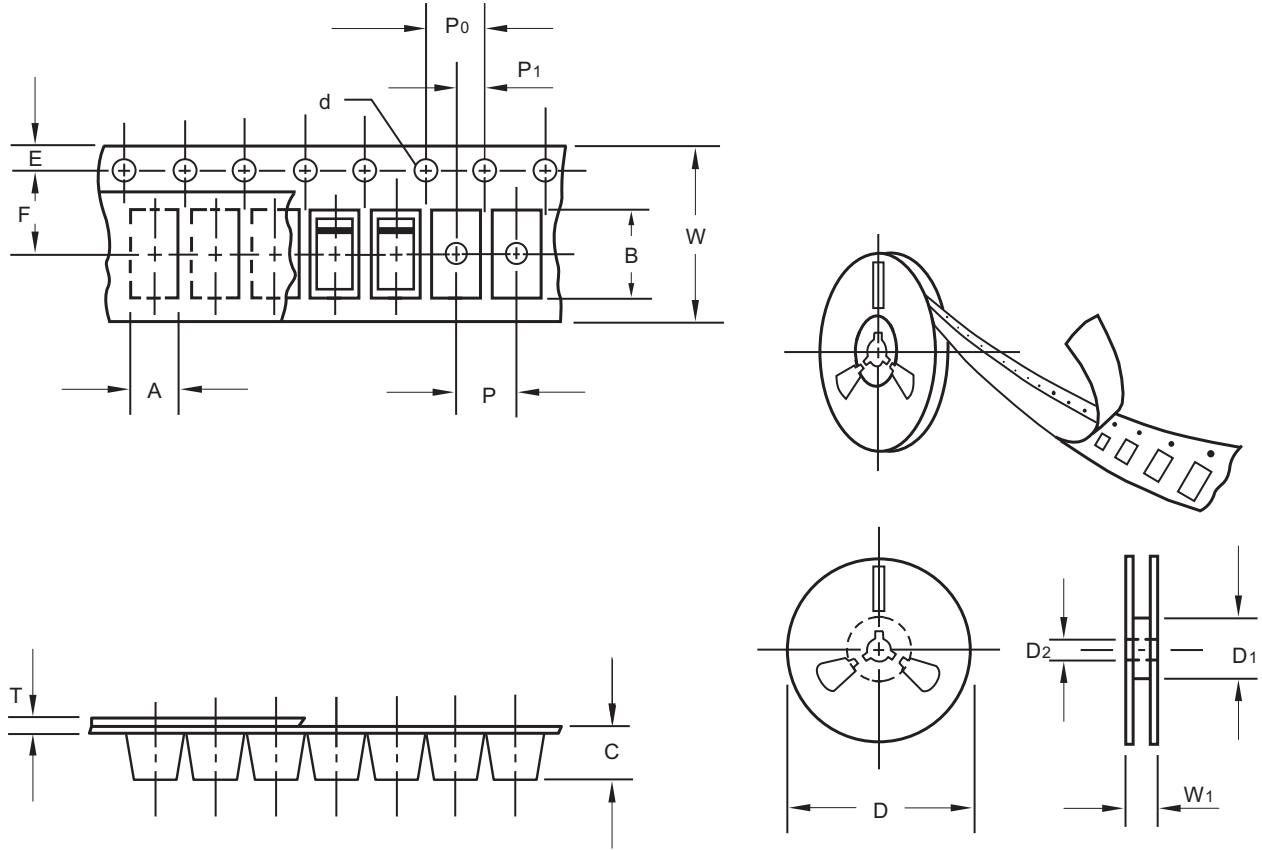
### Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA-L	0.110 (2.80)	0.059 (1.50)	0.110 (2.80)

**Packing information**



unit:mm

Item	Symbol	Tolerance	SMA-L
Carrier width	A	0.1	2.90
Carrier length	B	0.1	5.50
Carrier depth	C	0.1	2.10
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	12.00
Reel width	W1	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.